

S-5841 Series

Rev.2.2 02

TEMPERATURE SWITCH IC (THERMOSTAT IC)

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The S-5841 Series is a temperature switch IC (thermostat IC) which detects the temperature with a temperature accuracy of $\pm 2.5^{\circ}$ C. The output inverts when temperature reaches the detection temperature. The S-5841 Series restores the output voltage when the temperature drops to the level of release temperature.

The S-5841 Series operates at the lower power supply voltage of 2.2 V and its current consumption is 10 μ A typ. due to CMOS configuration.

A temperature sensor with the negative temperature coefficient, a reference voltage generation circuit, a comparator and a delay circuit are integrated on one chip, and enclosed into the packages SOT-23-5 and SNT-6A.

Features

- Detection temperature: $T_{DET} = +40^{\circ}C$ to $+100^{\circ}C$, $+1^{\circ}C$ step, detection accuracy: $\pm 2.5^{\circ}C$
- Low voltage operation: V_{DD} = 2.2 V min.

(Detection temperature = $+55^{\circ}$ C to $+100^{\circ}$ C, Ta = -40° C to $+100^{\circ}$ C)

- Low current consumption: $I_{DD} = 10 \ \mu A \ typ. \ (Ta = +25^{\circ}C)$
- Hysteresis temperature can be switched in 0°C, 2°C, 4°C and 10°C.
- Selectable output logic in active "H" or "L"
- Selectable output form in CMOS or Nch open drain
- Operation temperature range: $Ta = -40^{\circ}C \text{ to } +125^{\circ}C$
- Lead-free, Sn 100%, halogen-free*1

*1. Refer to "
Product Name Structure" for details.

Applications

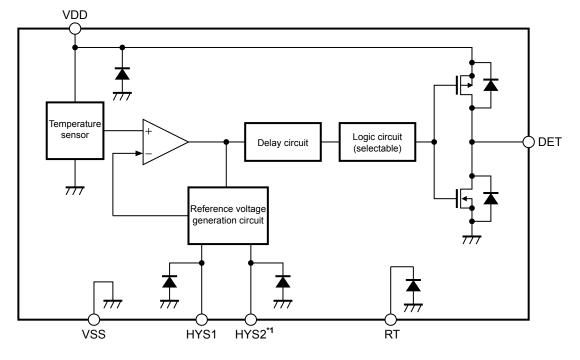
- Fan control
- Air conditioning system
- Various electronic devices

Packages

- SOT-23-5
- SNT-6A

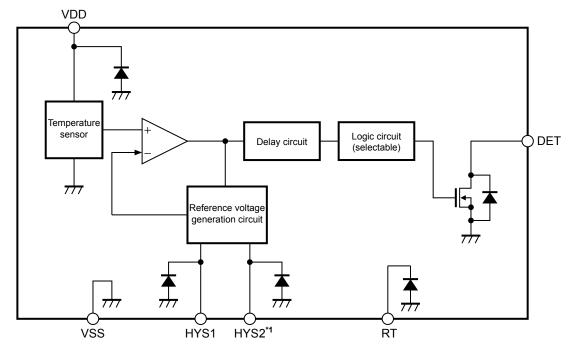
Block Diagrams

1. CMOS output product



*1. The HYS2 pin is not equipped for SOT-23-5.

Figure 1



2. Nch open drain output product

*1. The HYS2 pin is not equipped for SOT-23-5.

Figure 2

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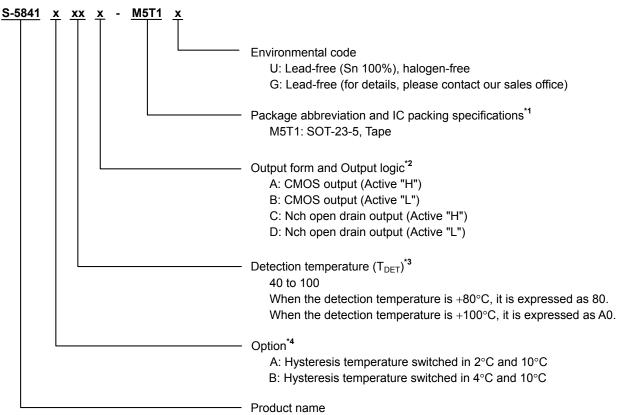
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Product Name Structure

Users are able to select the option for hysteresis temperature, detection temperature, output form and logic, package for the S-5841 Series.

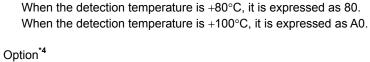
1. Product name





- ***1.** Refer to the tape drawing.
- *2. The DET pin output can be selected the output logic in active "H" or "L". The DET pin output can be selected the output form in CMOS or Nch open drain.
- *3. The detection temperature (T_{DET}) can be set in the range of +40°C to +100°C at 1°C step.
- *4. The hysteresis temperature is set by the HYS1 pin. By option, the hysteresis temperature of the product is selectable in 2°C and 10°C / 4°C and 10°C.

- S-5841 A xx x 16T1 U Environmental code U: Lead-free (Sn 100%), halogen-free Package abbreviation and IC packing specifications^{*1} I6T1: SNT-6A, Tape Output form and Output logic^{*2} A: CMOS output (Active "H") B: CMOS output (Active "H") C: Nch open drain output (Active "H") D: Nch open drain output (Active "L")
- 1.2 SNT-6A



A: Hysteresis temperature switched in 0°C, 2°C, 4°C and 10°C

Product name

40 to 100

- ***1.** Refer to the tape drawing.
- *2. The DET pin output can be selected the output logic in active "H" or "L". The DET pin output can be selected the output form in CMOS or Nch open drain.
- *3. The detection temperature (T_{DET}) can be set in the range of +40°C to +100°C at 1°C step.
- *4. The hysteresis temperature can be switched in 0°C, 2°C, 4°C, 10°C, and is set by the HYS1 pin and the HYS2 pin.

Detection temperature $(T_{DET})^{*3}$

2. Packages

Table 1	Package Drawing Codes
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Package Name	Dimension	Таре	Reel	Land
SOT-23-5	MP005-A-P-SD	MP005-A-C-SD	MP005-A-R-SD	_
SNT-6A	PG006-A-P-SD	PG006-A-C-SD	PG006-A-R-SD	PG006-A-L-SD

3. Product name list

3.1 SOT-23-5

Table 2

Product Name	Detection Temperature (T _{DET})	DET Pin Output Form	DET Pin Output Logic	Hysteresis Temperature (T _{HYS})
S-5841A55D-M5T1x	+55°C	Nch open drain	Active "L"	2°C, 10°C
S-5841A65D-M5T1x	+65°C	Nch open drain	Active "L"	2°C, 10°C
S-5841A75D-M5T1x	+75°C	Nch open drain	Active "L"	2°C, 10°C
S-5841A85D-M5T1x	+85°C	Nch open drain	Active "L"	2°C, 10°C
S-5841A95D-M5T1x	+95°C	Nch open drain	Active "L"	2°C, 10°C

Remark 1. Please contact our sales office for products other than those specified above.

2. x: G or U

3. Please select products of environmental code = U for Sn 100%, halogen-free products.

3.2 SNT-6A

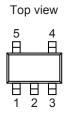
Table 3

Product Name	Detection Temperature (T _{DET})	DET Pin Output Form	DET Pin Output Logic	Hysteresis Temperature (T _{HYS})
S-5841A70A-I6T1U	+70°C	CMOS	Active "H"	0°C, 2°C, 4°C, 10°C
S-5841A80A-I6T1U	+80°C	CMOS	Active "H"	0°C, 2°C, 4°C, 10°C
S-5841A90A-I6T1U	+90°C	CMOS	Active "H"	0°C, 2°C, 4°C, 10°C
S-5841A50D-I6T1U	+50°C	Nch open drain	Active "L"	0°C, 2°C, 4°C, 10°C

Remark Please contact our sales office for products other than those specified above.

Pin Configurations

1. SOT-23-5



Pin No.	Symbol	Description
1	HYS1 ^{*1}	Hysteresis pin 1
2	VSS	GND pin
3	RT ^{*2}	Test pin
4	VDD	Power supply pin
5	DET	Output pin

Table 4

Figure 3

***1.** Fix the HYS1 pin as VDD pin or VSS pin in use.

*2. Set the RT pin open in use.

2. SNT-6A

Table 5

Pin No.	Symbol	Description
1	RT ^{*1}	Test pin
2	VSS	GND pin
3	HYS1 *2	Hysteresis pin 1
4	DET	Output pin
5	HYS2 ^{*2}	Hysteresis pin 2
6	VDD	Power supply pin

***1.** Set the RT pin open in use.

*2. Fix the HYS1 pin and the HYS2 pin as VDD pin or VSS pin in use.



Figure 4

1 2 3

Absolute Maximum Ratings

Table 6

(Ta = +25°C unless otherwise speci							
Item		Symbol	Absolute Maximum Rating	Unit			
Power supply voltage	ge (V _{SS} = 0 V)	V _{DD}	V _{SS} + 12	V			
Pin voltage		V _{RT} , V _{HYS1} , V _{HYS2}	$V_{\text{SS}}-0.3$ to $V_{\text{DD}}+0.3$	V			
Outentuckter	CMOS output product	N/	$V_{\text{SS}}-0.3$ to $V_{\text{DD}}+0.3$	V			
Output voltage	Nch open drain product	V _{DET}	$V_{\text{SS}}-0.3$ to $V_{\text{SS}}+12.0$	V			
Dewer dissigntion	SOT-23-5		600 ^{*1}	mW			
Power dissipation	SNT-6A	- P _D	400 ^{1*}	mW			
Operating ambient	Operating ambient temperature		-40 to +125	°C			
Storage temperatur	e	T _{stg}	–55 to +150	°C			

*1. When mounted on board

[Mounted board]

(1) Board size : $114.3 \text{ mm} \times 76.2 \text{ mm} \times t1.6 \text{ mm}$

(2) Board name : JEDEC STANDARD51-7

Caution The absolute maximum ratings are rated values exceeding which the product could suffer physical damage. These values must therefore not be exceeded under any conditions.

■ DC Electrical Characteristics

1. CMOS output product

1.1 SOT-23-5

Table 7

		Tabl		(Ta = -	+25°C.	unless other	rwise si	pecified)
Item	Symbol	Conditio	on	Min.	Тур.	Max.	Unit	Test circuit
Power supply voltage ^{*1}	V	T _{DET} = +55°C to +10	0°C	2.2	-	10.0	V	1
Power supply voltage	V _{DD}	T _{DET} = +40°C to +54	°C	2.6	-	10.0	V	1
Detection temperature	+T _D	-		$T_{\text{DET}}-2.5$	T_{DET}	$T_{\text{DET}} + 2.5$	°C	1
Hysteresis of detection temperature ^{*2}		Hysteresis option	HYS1	-	_	-	_	-
		٨	"H"	_	2	_	°C	1
	T _{HYS}	A	"L"	_	10	_	°C	1
temperature		В	"H"	_	4	_	°C	1
			"L"	_	10	_	°C	1
Output ourroat	IDETH	V _{DD} = 3.0 V,	V _{DET} = 2.2 V	2	9.4	_	mA	2
Output current	IDETL	apply to DET pin	V _{DET} = 0.4 V	0.5	2.3	_	mA	2
Current consumption during operation	I _{DD}	V _{DD} = 3.0 V		_	10	20	μA	1
HYS1 pin input voltage "H"	V _{IH1}	_		$0.8\times V_{\text{DD}}$	-	_	V	3
HYS1 pin input voltage "L"	V _{IL1}	-			-	$0.2\times V_{\text{DD}}$	V	3
HYS1 pin input current "H"	I _{IH1}	V _{DD} = 3.0 V, V _{HYS1} =	= 3.0 V	-0.1	_	0.1	μA	3
HYS1 pin input current "L"	I _{IL1}	V _{DD} = 3.0 V, V _{HYS1} =	= 0 V	-0.1	-	0.1	μA	3

*1. The minimum operation voltages are as follows under the operation ambient temperature over +100°C. $V_{DD} = 2.3 \text{ V}$ min. (Detection temperature = +55°C to +100°C) $V_{DD} = 2.7 \text{ V}$ min. (Detection temperature = +40°C to +54°C)

 *2. The hysteresis temperature can be set by the HYS1 pin. These two types are selectable by option. Hysteresis option A: 2°C of hysteresis temperature during HYS1 = "H", 10°C of hysteresis temperature during HYS1 = "L"

Hysteresis option B: 4°C of hysteresis temperature during HYS1 = "H", 10°C of hysteresis temperature during HYS1 = "L"

[Fahrenheit \Leftrightarrow Celsius Conversion equation]

 $\label{eq:constraint} \begin{array}{l} \label{eq:constraint} \begin{tabular}{l} \begin{tabular}{l}$

Rev.2.2_02

TEMPERATURE SWITCH IC (THERMOSTAT IC) S-5841 Series

0 = 0

1.2 SNT-6A

Table 8

				(Ta =	+25°C,	unless other	rwise s	pecified)
Item	Symbol	Conditio	on	Min.	Тур.	Max.	Unit	Test circuit
Device events in the set*1		T _{DET} = +55°C to +10	0°C	2.2	_	10.0	V	1
Power supply voltage ^{*1}	V _{DD}	T _{DET} = +40°C to +54	°C	2.6	-	10.0	V	1
Detection temperature	+T _D			T _{DET} - 2.5	T _{DET}	$T_{DET} + 2.5$	°C	1
		HYS1	HYS2	_	-	_	١	_
Liveteracia of data stice		"H"	"H"	_	2	-	°C	1
Hysteresis of detection temperature ^{*2}	T _{HYS}	"H"	"L"	-	4	-	°C	1
		"L"	"H"	-	10	-	°C	1
		"L"	"L"	-	0	-	°C	1
Output ourseat	IDETH	V _{DD} = 3.0 V,	V _{DET} = 2.2 V	2	9.4	-	mA	2
Output current	IDETL	apply to DET pin	V _{DET} = 0.4 V	0.5	2.3	-	mA	2
Current consumption during operation	I _{DD}	$V_{DD} = 3.0 V$		-	10	20	μA	1
HYS1 pin input voltage "H"	V _{IH1}	-		$0.8\times V_{\text{DD}}$	_	-	V	3
HYS1 pin input voltage "L"	V _{IL1}	_		-	_	$0.2\times V_{\text{DD}}$	V	3
HYS1 pin input current "H"	I _{IH1}	V _{DD} = 3.0 V, V _{HYS1} :	= 3.0 V	-0.1	-	0.1	μA	3
HYS1 pin input current "L"	I _{IL1}	V _{DD} = 3.0 V, V _{HYS1} =	= 0 V	-0.1	_	0.1	μA	3
HYS2 pin input voltage "H"	V _{IH2}	-		$0.8\times V_{\text{DD}}$	-	_	V	3
HYS2 pin input voltage "L"	V _{IL2}	_		-	_	$0.2\times V_{\text{DD}}$	V	3
HYS2 pin input current "H"	I _{IH2}	V _{DD} = 3.0 V, V _{HYS2} =	= 3.0 V	-0.1	-	0.1	μA	3
HYS2 pin input current "L"	I _{IL2}	V _{DD} = 3.0 V, V _{HYS2} =	= 0 V	-0.1	-	0.1	μA	3

*1. The minimum operation voltages are as follows under the operation ambient temperature over +100°C. $V_{DD} = 2.3 \text{ V}$ min. (Detection temperature = +55°C to +100°C) $V_{DD} = 2.7 \text{ V}$ min. (Detection temperature = +40°C to +54°C)

*2. The hysteresis temperature can be switched in 0°C, 2°C, 4°C, 10°C, and is set by the HYS1 pin and HYS2 pin.

[Fahrenheit \Leftrightarrow Celsius Conversion equation]

 $^{\circ}C$ = ($^{\circ}F - 32$) × 5 / 9 $^{\circ}F$ = 32 + $^{\circ}C$ × 9 / 5

TEMPERATURE SWITCH IC (THERMOSTAT IC) S-5841 Series

2. Nch open drain output

2.1 SOT-23-5

Table 9

		Table		(Ta =	+25°C	unless other	wise sr	pecified)
Item	Symbol	Conditio	on	Min.	Тур.	Max.	Unit	Test circuit
Power supply voltage ^{*1}	V	T _{DET} = +55°C to +10	0°C	2.2	-	10.0	V	1
Power supply voltage	V _{DD}	T _{DET} = +40°C to +54	°C	2.6	-	10.0	V	1
Detection temperature	+T _D	-		$T_{\text{DET}} - 2.5$	T _{DET}	$T_{\text{DET}} + 2.5$	°C	1
Hysteresis of detection temperature* ²		Hysteresis option	HYS1	-	-	-	-	—
		٨	"H"	-	2	_	°C	1
	T _{HYS}	A	"L"	-	10	_	°C	1
temperature		P	"H"	-	4	_	°C	1
		В	"L"	-	10	_	°C	1
Output current	I _{DETL}	V _{DET} = 0.4 V, V _{DD} =	3.0 V	0.5	2.3	_	mA	2
Leakage current	I _{LEAK}	V _{DET} = 10.0 V, V _{DD}	= 3.0 V	-	-	100	nA	2
Current consumption during operation	I _{DD}	V _{DD} = 3.0 V		_	10	20	μA	1
HYS1 pin input voltage "H"	V _{IH1}	_		$0.8\times V_{\text{DD}}$	-	-	V	3
HYS1 pin input voltage "L"	V _{IL1}	_		_	_	$0.2\times V_{\text{DD}}$	V	3
HYS1 pin input current "H"	I _{IH1}	V _{DD} = 3.0 V, V _{HYS1} =	V _{DD} = 3.0 V, V _{HYS1} = 3.0 V		-	0.1	μA	3
HYS1 pin input current "L"	I _{IL1}	V _{DD} = 3.0 V, V _{HYS1} =	= 0 V	-0.1	-	0.1	μA	3

*1. The minimum operation voltages are as follows under the operation ambient temperature over +100°C. $V_{DD} = 2.3 \text{ V} \text{ min.}$ (Detection temperature = +55°C to +100°C)

 $V_{DD} = 2.7 V \text{ min.}$ (Detection temperature = +40°C to +54°C)

 *2. The hysteresis temperature can be set by the HYS1 pin. These two types are selectable by option. Hysteresis option A: 2°C of hysteresis temperature during HYS1 = "H", 10°C of hysteresis temperature during HYS1 = "L" Hysteresis option B: 4°C of hysteresis temperature during HYS1 = "H", 10°C of hysteresis temperature during HYS1 = "L"

[Fahrenheit ⇔ Celsius Conversion equation]

 $^{\circ}C = (^{\circ}F - 32) \times 5 / 9$ $^{\circ}F = 32 + ^{\circ}C \times 9 / 5$

TEMPERATURE SWITCH IC (THERMOSTAT IC) S-5841 Series

2.2 SNT-6A

Table 10

		Idble		(Ta =	+25°C,	unless other	wise s	pecified)
Item	Symbol	Conditio	on	Min.	Тур.	Max.	Unit	Test circuit
Device events vielte es*1	V	T _{DET} = +55°C to +10	0°C	2.2	-	10.0	V	1
Power supply voltage ^{*1}	V _{DD}	T _{DET} = +40°C to +54	°C	2.6		10.0	V	1
Detection temperature	+T _D	_		$T_{\text{DET}}-2.5$	T _{DET}	$T_{\text{DET}} + 2.5$	°C	1
		HYS1	HYS2	-	_	_	-	_
Livetoresis of data stice		"H"	"H"	-	2	_	°C	1
Hysteresis of detection temperature ^{*2}	T _{HYS}	"H"	"L"	_	4	_	°C	1
lemperature		"L"	"H"	-	10	_	°C	1
		"L"	"L"	-	0	_	°C	1
Output current	IDETL	V _{DET} = 0.4 V, V _{DD} =	3.0 V	0.5	2.3	_	mA	2
Leakage current	I _{LEAK}	V _{DET} = 10.0 V, V _{DD}	= 3.0 V	_	-	100	nA	2
Current consumption during operation	I _{DD}	V _{DD} = 3.0 V		_	10	20	μA	1
HYS1 pin input voltage "H"	V _{IH1}	-		$0.8\times V_{\text{DD}}$		_	V	3
HYS1 pin input voltage "L"	V _{IL1}	_		-	1	$0.2\times V_{\text{DD}}$	V	3
HYS1 pin input current "H"	I _{IH1}	V _{DD} = 3.0 V, V _{HYS1} =	= 3.0 V	-0.1	1	0.1	μA	3
HYS1 pin input current "L"	I _{IL1}	$V_{DD} = 3.0 \text{ V}, \text{ V}_{HYS1} = 0 \text{ V}$		-0.1	1	0.1	μA	3
HYS2 pin input voltage "H"	V _{IH2}	_		$0.8 \times V_{\text{DD}}$	I	_	V	3
HYS2 pin input voltage "L"	V _{IL2}	-	_		-	$0.2\times V_{\text{DD}}$	V	3
HYS2 pin input current "H"	I _{IH2}	V _{DD} = 3.0 V, V _{HYS2} =	= 3.0 V	-0.1	-	0.1	μA	3
HYS2 pin input current "L"	I _{IL2}	V _{DD} = 3.0 V, V _{HYS2} =	= 0 V	-0.1	-	0.1	μA	3

*1. The minimum operation voltages are as follows under the operation ambient temperature over +100°C.

 V_{DD} = 2.3 V min. (Detection temperature = +55°C to +100°C)

 V_{DD} = 2.7 V min. (Detection temperature = +40°C to +54°C)

*2. The hysteresis temperature can be switched in 0°C, 2°C, 4°C, 10°C, and is set by the HYS1 pin and HYS2 pin.

[Fahrenheit ⇔ Celsius Conversion equation]

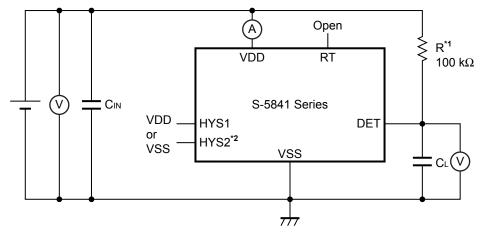
 $^{\circ}C$ = ($^{\circ}F - 32$) × 5 / 9 $^{\circ}F$ = 32 + $^{\circ}C$ × 9 / 5

■ AC Electrical Characteristics

Table 11

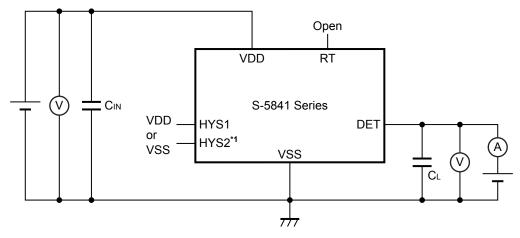
Item	Symbol	Condition	Min.	Тур.	Max.	Unit	Test circuit
Noise suppression time	t _{delay}	V_{DD} = 3.0 V, Ta = detection temperature	_	380	_	μS	-

Test Circuits



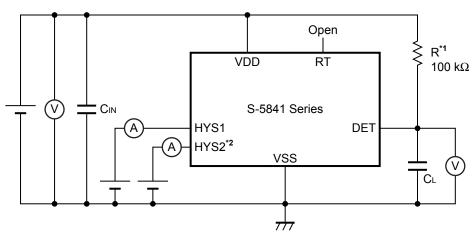
- *1. Resistor (R) is unnecessary for the CMOS output product.
- *2. The HYS2 pin is not equipped for SOT-23-5.

Figure 5 Test Circuit 1



*1. The HYS2 pin is not equipped for SOT-23-5.

Figure 6 Test Circuit 2



- ***1.** Resistor (R) is unnecessary for the CMOS output product.
- *2. The HYS2 pin is not equipped for SOT-23-5.
 - Figure 7 Test Circuit 3

Operation

1. Basic operation

The S-5841 Series is a temperature switch IC (thermostat IC) which detects a certain temperature and sends a signal to an external device. Various combinations of the parameters such as the detection temperature, output form and output logic can be selected.

Following is about the operation when the DET pin output logic is active "H".

After applying the power supply, the S-5841 Series starts to detect the temperature. If it is lower than the detection temperature $(+T_D)$, the DET pin output keeps "L". The temperature rises and exceeds the detection temperature, the DET pin is set to "H".

After the detection, the temperature drops and reaches the release temperature $(+T_D - T_{HYS})$, the DET pin returns to "L". **Figure 8** is the timing chart.

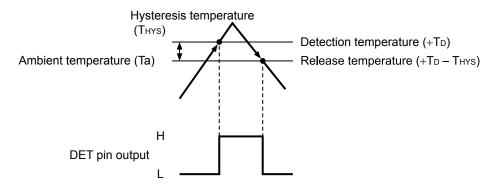


Figure 8 Operation when DET Pin Output Logic is Active "H"

2. Hysteresis setting

2.1 SOT-23-5

The hysteresis temperature can be set by the HYS1 pin. By option, the hysteresis temperature of the product is selectable in 2° C and 10° C / 4° C and 10° C.

Setting Pin	l luchana dia T anàna amatana	
HYS1	Hysteresis Temperature	
"H"	2°C	
"_"	10°C	

Table 12	Hysteresis Option A	
	Trysleresis Option P	•

	Table 13	Hysteresis Option E	3
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Setting Pin		
HYS1	Hysteresis Temperature	
"H"	4°C	
"L"	10°C	

2.2 SNT-6A

The hysteresis temperature can be switched in 0°C, 2°C, 4°C, 10°C, and is set by the HYS1 pin and HYS2 pin.

Setting Pin		Libertana dia Tanàna amin'ny
HYS1	HYS2	Hysteresis Temperature
"H"	"H"	2°C
"H"	"L"	4°C
"L"	"H"	10°C
"L"	"L"	0°C

Table 14Hysteresis Option A

3. Delay circuit

The S-5841 Series sets the noise suppression time (t_{delay}) via the delay circuit. By this, the S-5841 Series prevents false detection operations of the DET pin output.

The followings are about the operation when the DET pin output logic is active "H".

3.1 The temperature is the detection temperature or less

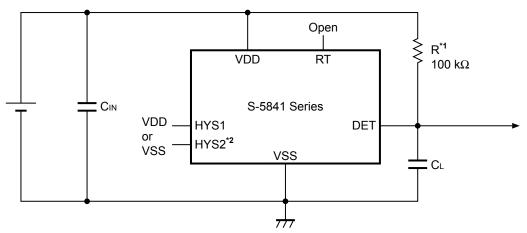
The output from a comparator is "H", and the DET pin is "L". Due to noise or others, the output from a comparator is inverted to "L" once; however, the DET pin keeps "L" if this status is t_{delay} or shorter.

3.2 The temperature exceeds the detection temperature

The output from a comparator gets "L". And the DET pin gets "H" after the period has passed t_{delay} or longer.

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Standard Circuit



- *1. Resistor (R) is unnecessary for the CMOS output product.
- ***2.** The HYS2 pin is not equipped with SOT-23-5.

Figure 9

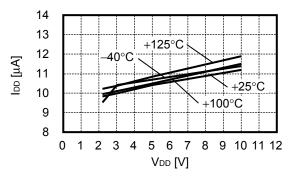
Caution The above connection diagram will not guarantee successful operation. Perform thorough evaluation using actual application to set the constant.

Precautions

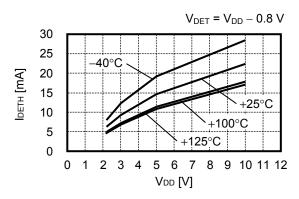
- Set a capacitor (C_{IN}) of 0.1 μ F or more between the VDD and VSS pin for stabilization.
- Set a capacitor (C_L) of about 1 μF for the DET pin to prevent malfunction caused by the noise when the power supply is applied.
- The S-5841 Series may oscillate by setting a capacitor to the RT pin. Set the RT pin open in use.
- If the RT pin is short-circuited to VSS, the DET pin becomes active in the S-5841 Series.
- Fix the HYS1 pin and the HYS2 pin VDD or VSS in use.
- Do not apply an electrostatic discharge to this IC that exceeds the performance ratings of the built-in electrostatic
 protection circuit.
- ABLIC Inc. claims no responsibility for any disputes arising out of or in connection with any infringement by
 products, including this IC, of patents owned by a third party.

Characteristics (Typical Data)

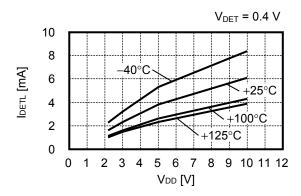
1. Current consumption vs. Power supply voltage characteristics



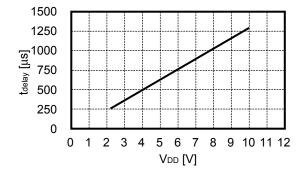
2. DET pin current "H" vs. Power supply voltage characteristics (CMOS output product only)



3. DET pin current "L" vs. Power supply voltage characteristics



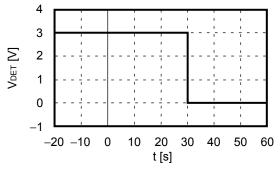
4. Noise suppression time vs. Power supply voltage characteristics



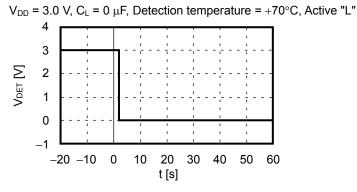
Rev.2.2_02

- 5. Response against heat (Output voltage vs. Time)
 - 5.1 When packages are put into the air of +100 degrees from the air of +25 degrees at t = 0 s



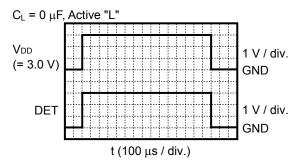


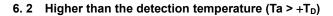
5. 2 When packages are put into the liquid of +100 degrees from the air of +25 degrees at t = 0 s

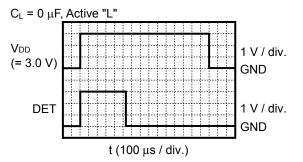


6. Response against startup



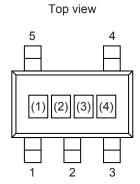






Marking Specifications

1. SOT-23-5



(1) to (3): (4): Product code (refer to **Product name vs. Product code**) Lot number

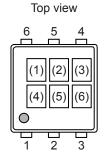
Product name vs. Product code

Dreduct Name	Product Code		
Product Name	(1)	(2)	(3)
S-5841A55D-M5T1x	Т	Н	В
S-5841A65D-M5T1x	Т	Н	С
S-5841A75D-M5T1x	Т	Н	D
S-5841A85D-M5T1x	Т	Н	Е
S-5841A95D-M5T1x	Т	Н	F

Remark1. x: G or U

2. Please select products of environmental code = U for Sn 100%, halogen-free products.

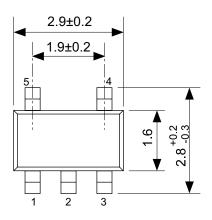
2. SNT-6A

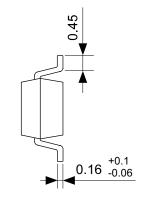


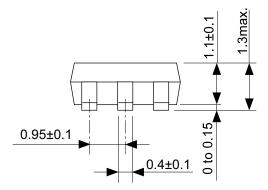
(1) to (3): (4) to (6): Product code (refer to **Product name vs. Product code**) Lot number

Product name vs. Product code

Product Name	Product Code		
Product Name	(1)	(2)	(3)
S-5841A70A-I6T1U	Т	Ι	G
S-5841A80A-I6T1U	Т	Ι	Н
S-5841A90A-I6T1U	Т	Ι	Ι
S-5841A50D-I6T1U	Т	Н	A

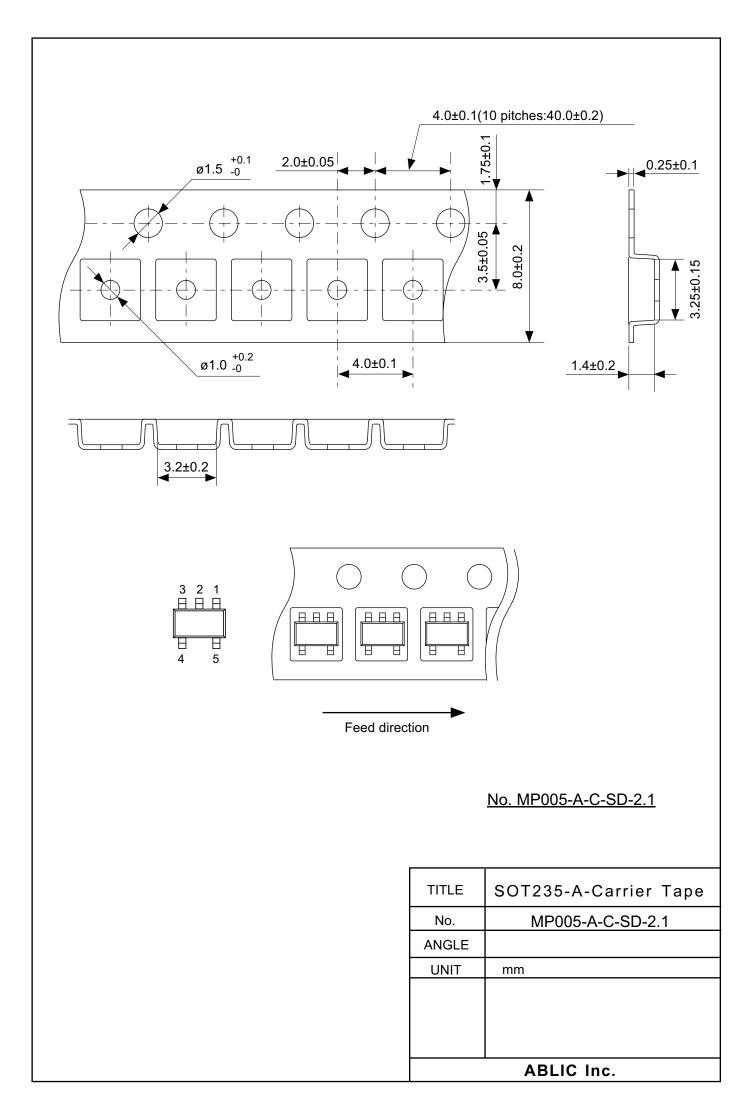


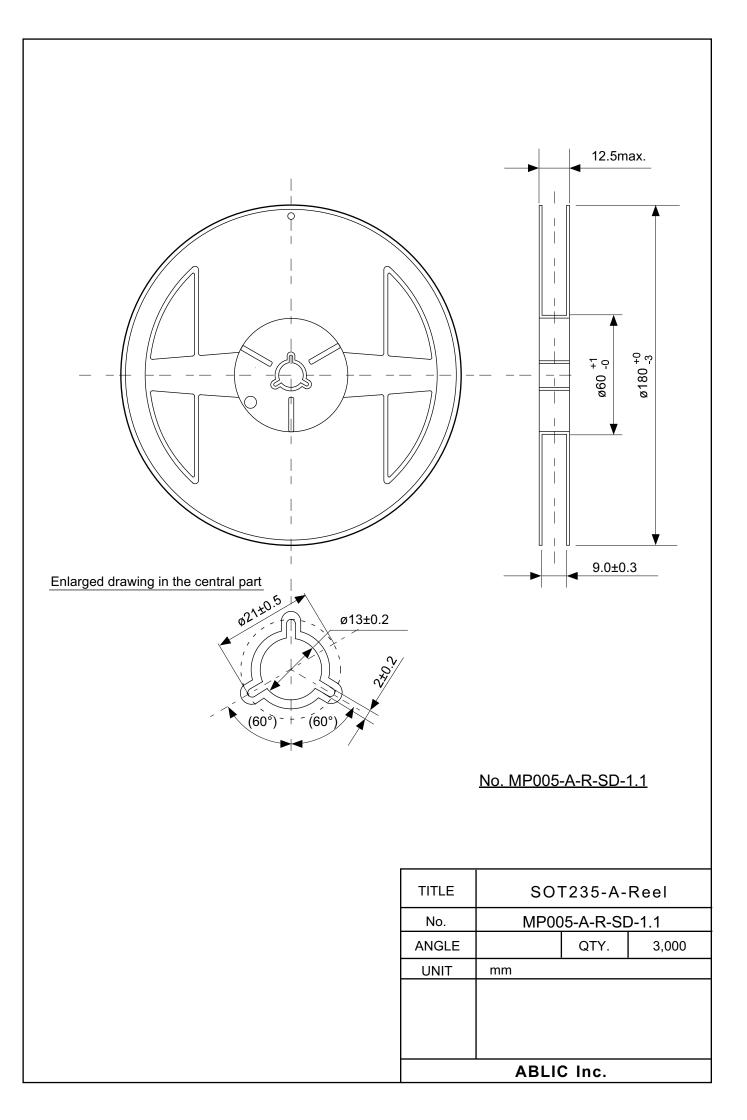


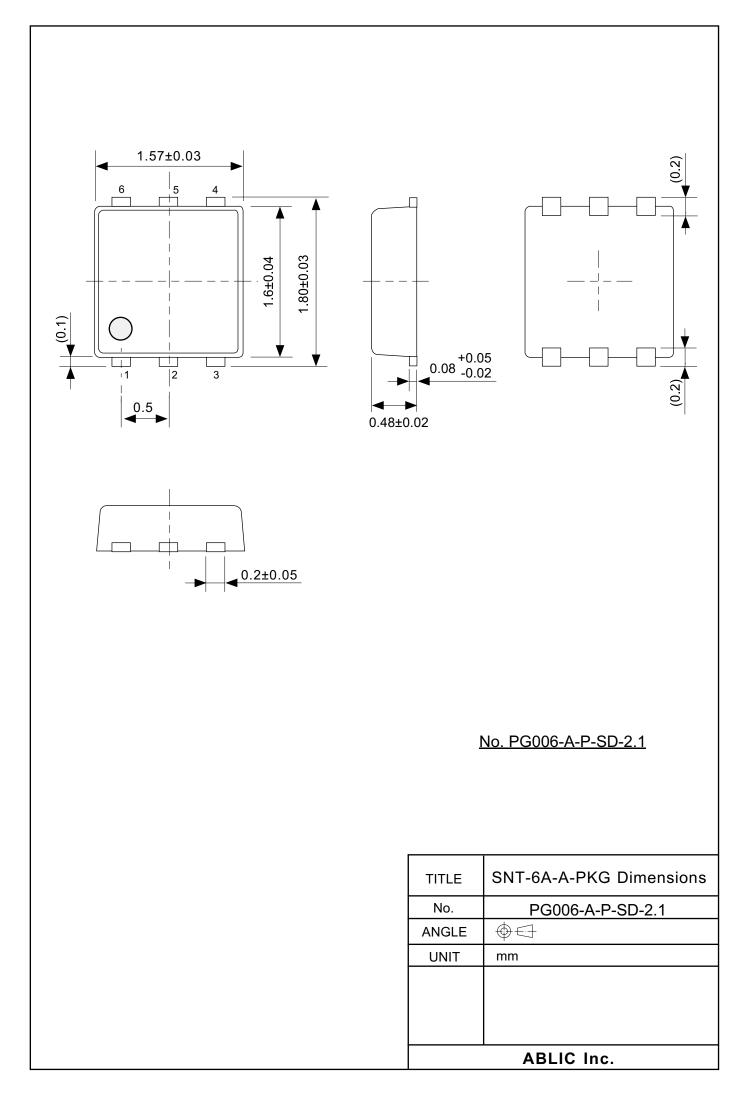


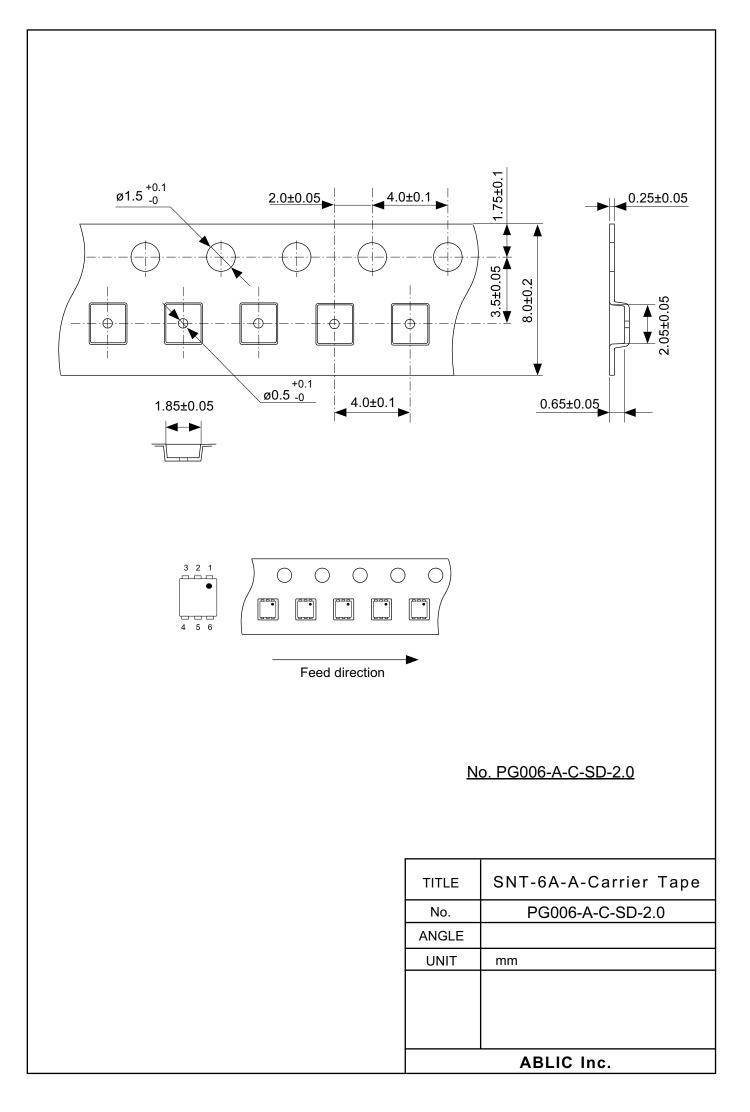
No. MP005-A-P-SD-1.3

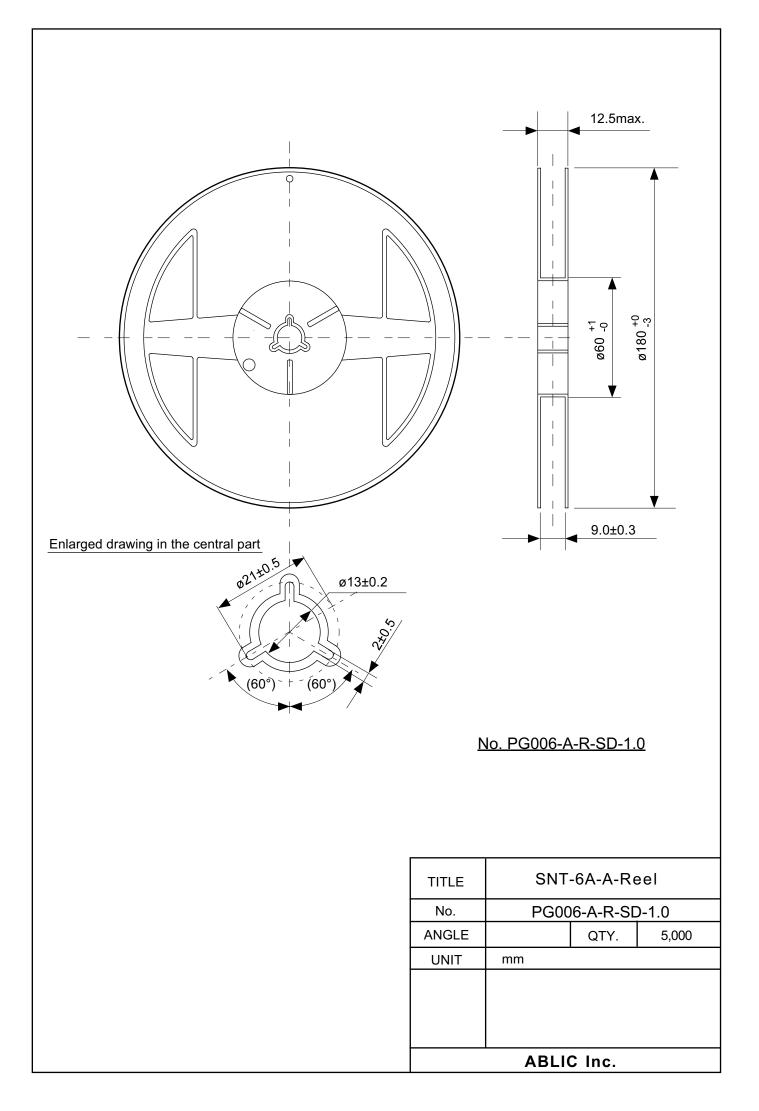
TITLE	SOT235-A-PKG Dimensions
No.	MP005-A-P-SD-1.3
ANGLE	
UNIT	mm
ABLIC Inc.	

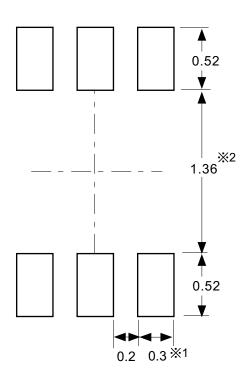












※1. ランドパターンの幅に注意してください (0.25 mm min. / 0.30 mm typ.)。 ※2. パッケージ中央にランドパターンを広げないでください (1.30 mm ~ 1.40 mm)。

- 注意 1. パッケージのモールド樹脂下にシルク印刷やハンダ印刷などしないでください。
 - 2. パッケージ下の配線上のソルダーレジストなどの厚みをランドパターン表面から0.03 mm 以下にしてください。
 - 3. マスク開ロサイズと開口位置はランドパターンと合わせてください。
 - 4. 詳細は "SNTパッケージ活用の手引き" を参照してください。

%1. Pay attention to the land pattern width (0.25 mm min. / 0.30 mm typ.).

%2. Do not widen the land pattern to the center of the package (1.30 mm ~ 1.40 mm).

- Caution 1. Do not do silkscreen printing and solder printing under the mold resin of the package.
 2. The thickness of the solder resist on the wire pattern under the package should be 0.03 mm or less from the land pattern surface.
 - 3. Match the mask aperture size and aperture position with the land pattern.
 - 4. Refer to "SNT Package User's Guide" for details.
- ※1. 请注意焊盘模式的宽度 (0.25 mm min. / 0.30 mm typ.)。
- ※2. 请勿向封装中间扩展焊盘模式 (1.30 mm~1.40 mm)。
- 注意 1. 请勿在树脂型封装的下面印刷丝网、焊锡。
 - 2. 在封装下、布线上的阻焊膜厚度 (从焊盘模式表面起) 请控制在 0.03 mm 以下。
 - 3. 钢网的开口尺寸和开口位置请与焊盘模式对齐。
 - 4. 详细内容请参阅 "SNT 封装的应用指南"。

TITLE	SNT-6A-A -Land Recommendation
No.	PG006-A-L-SD-4.1
ANGLE	
UNIT	mm
ABLIC Inc.	

No. PG006-A-L-SD-4.1

Disclaimers (Handling Precautions)

- 1. All the information described herein (product data, specifications, figures, tables, programs, algorithms and application circuit examples, etc.) is current as of publishing date of this document and is subject to change without notice.
- The circuit examples and the usages described herein are for reference only, and do not guarantee the success of any specific mass-production design.
 ABLIC Inc. is not responsible for damages caused by the reasons other than the products described herein

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- 3. ABLIC Inc. is not responsible for damages caused by the incorrect information described herein.
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Prior consultation with our sales office is required when considering the above uses.

ABLIC Inc. is not responsible for damages caused by unauthorized or unspecified use of our products.

9. Semiconductor products may fail or malfunction with some probability. The user of the products should therefore take responsibility to give thorough consideration to safety design including redundancy, fire spread prevention measures, and malfunction prevention to prevent accidents causing injury or death, fires and social damage, etc. that may ensue from the products' failure or malfunction. The entire system must be sufficiently evaluated and applied on customer's own responsibility.

- 10. The products are not designed to be radiation-proof. The necessary radiation measures should be taken in the product design by the customer depending on the intended use.
- 11. The products do not affect human health under normal use. However, they contain chemical substances and heavy metals and should therefore not be put in the mouth. The fracture surfaces of wafers and chips may be sharp. Be careful when handling these with the bare hands to prevent injuries, etc.
- 12. When disposing of the products, comply with the laws and ordinances of the country or region where they are used.
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